## [What Is Claimed Is]

- 1. A film-forming apparatus characterized by having means for irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light.
- 2. A film-forming apparatus characterized by having a lamp light source for irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light.
  - 3. A film-forming apparatus according to claim 2, characterized in that the lamp light source is in a rectangular or oblong shape.
- 4. A film-forming apparatus characterized by having means for heating a component provided in a film-forming chamber with radiation heat.
  - 5. A film-forming apparatus, characterized in that a component provided in a film-forming chamber is equipped with a conductor for heating the component with radiation heat.
- 6. A film-forming apparatus according to claim 1, characterized in that the component is an adhesion preventing shield.
  - 7. A film-forming apparatus according to claim 1, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

- 8. A film-forming apparatus according to claim 7, characterized in that plasma is generated in the exhaust treatment chamber.
- 9. A method of cleaning a film-forming apparatus, comprising the steps of: irradiating a component provided in a film-forming chamber with at least one selected from the group consisting of infrared light, UV-light, and visible light, thereby sublimating a vapor-deposition material adhering to the component; and exhausting the sublimated evaporation material.
- 10. A method of cleaning according to claim 9, characterized in that at least one selected from the group consisting of the infrared light, UV-light, and visible
  10 light is radiated by using a lamp light source provided in the film-forming chamber.
  - 11. A method of cleaning according to claim 9, characterized in that an irradiation surface of at least one selected from the group consisting of the infrared light, UV-light, and visible light is in a rectangular or oblong shape.
- 12. A method of cleaning according to claim 9, characterized in that, in the sublimation step, gas containing a halogen-group element is flowed in the film-forming chamber.
  - 13. A method of cleaning according to claim 9, characterized in that the sublimated vapor-deposition material is exposed to plasma during exhaust.
    - 14. A method of cleaning according to claim 13, characterized in that the

plasma is oxygen plasma.

- 15. A method of cleaning according to claim 9, characterized in that the vapor-deposition material is an organic EL material.
- 16. A method of manufacturing an electro-optical device including the method of cleaning of claim 9.
  - 17. A method of manufacturing an electro-optical device including the method of cleaning of claim 9.
  - 18. A film-forming apparatus according to claim 2, characterized in that the component is an adhesion preventing shield.
- 19. A film-forming apparatus according to claim 2, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.
  - 20. A film-forming apparatus according to claim 19, characterized in that plasma is generated in the exhaust treatment chamber.
- 21. A film-forming apparatus according to claim 4, characterized in that the component is an adhesion preventing shield.
  - 22. A film-forming apparatus according to claim 4, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.

- 23. A film-forming apparatus according to claim 22, characterized in that plasma is generated in the exhaust treatment chamber.
- 24. A film-forming apparatus according to claim 5, characterized in that the component is an adhesion preventing shield.
- 25. A film-forming apparatus according to claim 5, characterized in that an exhaust treatment chamber is connected to the film-forming chamber.
  - 26. A film-forming apparatus according to claim 25, characterized in that plasma is generated in the exhaust treatment chamber.